

Title (en)
SEMICONDUCTOR WAFER LEVEL PACKAGE

Title (de)
HALBLEITERVERPACKUNG AUF WAFEREBENE

Title (fr)
BOITIER SUR TRANCHE (WLP) DE SEMICONDUCTEUR

Publication
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Application
EP 00961925 A 20000915

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Abstract (en)
[origin: WO0120671A1] A semiconductor wafer level package used to encapsulate a device fabricated on a semiconductor substrate wafer (11) before dicing of the wafer into individual chips. A cap wafer (16) may be bonded to the semiconductor substrate using a low temperature frit glass layer (14) as a bonding agent. The frit glass layer (14) is in direct contact with the device. A hermetic seal is formed by a combination of the semiconductor substrate wafer (11), the cap wafer (16) and the first glass layer (14). A second embodiment of the package (21) does not contain a cap wafer.

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IPC 8 full level
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